Sony SI-F209 SMT Pick and Place Machine for 50x50mm to 460x360mm Substrates

Our Product Introduction

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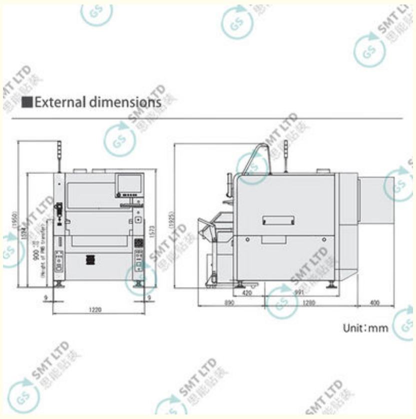
Basic Information

Place of Origin:	Japan
Brand Name:	Sony
Model Number:	SI-F209
Minimum Order Quantity:	1 PCS
Price:	USD+negotiable+pcs
Packaging Details:	1350*1850*1650mm
Delivery Time:	1-7 days
Payment Terms:	T/T
Supply Ability:	1+pcs+per days

Product Specification

Model:	Sony SI-F209
Substrate Size:	50mm*50mm-460mm*360mm
Substrate Thickness:	0.5mmto2.6mm
Number Of Mounting Heads:	1 Head 6 Nozzles
Mounting Range:	2012(0804)-32mmIC
Component Height:	Max 7mm Mobile Camera Fixed Camera 25mm
Mounting Speed:	0.49sec(7350CPH)
Mounting Accuracy:	60um (CPK1.0 Or Above) Chip)
Power Supply:	AC3-phase 200V±10% 50/60HZ
Power Consumption:	2.3kw
Gas Consumption:	0.49MPA 100L/min
Appearance Size:	1220mm*1700mm*1573mm
Weight:	1800KG
Machine Size:	



Product Description

Sony SI-F209 SMT Pick And Place Machine for Substrate Size 50mm*50mm-460mm*360mm Maximum Load 1800KG

Product Specifications

Attribute	Value
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Machine Size	1220*1700*1588mm

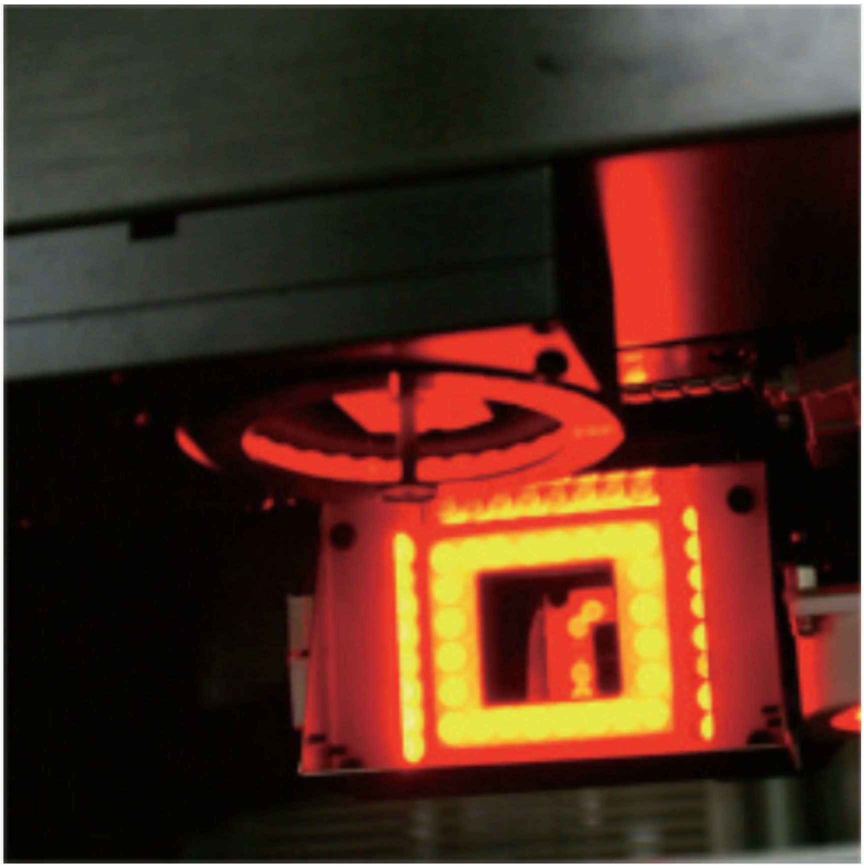
Product Description

Enhance your PCB assembly with the Sony SI-F209, a cutting-edge SMT mounter renowned for its precision and high-speed capabilities. With a robust modular design that allows for rapid reconfiguration, this machine is an ideal solution for electronics manufacturers seeking to maximize productivity and reduce placement costs. It boasts an adaptable feeder system capable of handling a diverse array of components, ensuring seamless integration into any SMT line. The SI-F209's advanced vision system guarantees exact alignment and placement, driving efficiency even for complex boards. Rely on Sony's innovation to meet the demanding standards of modern SMT production with this versatile mounter.

Key Features

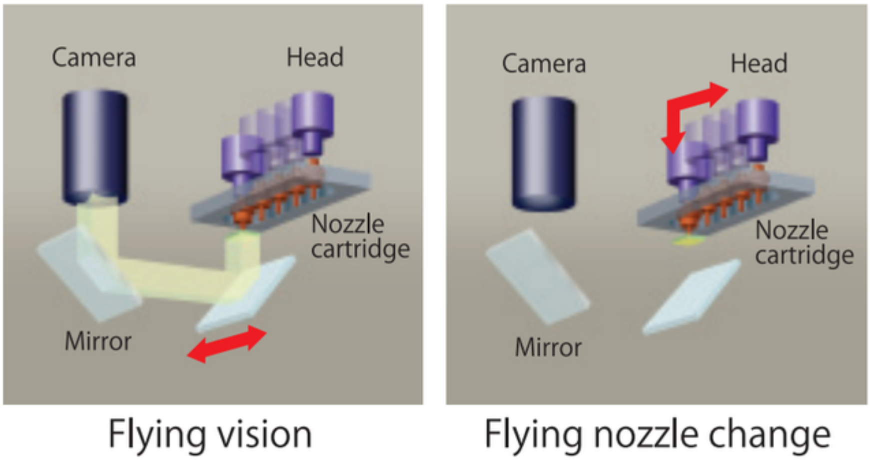
Supports large, odd-shaped parts

The unit is equipped with a multifunction head that is capable of mounting parts ranging from size 2012 to φ150mm. The unit also automatically corrects the pick up position on the parts to improve the pick up rate.



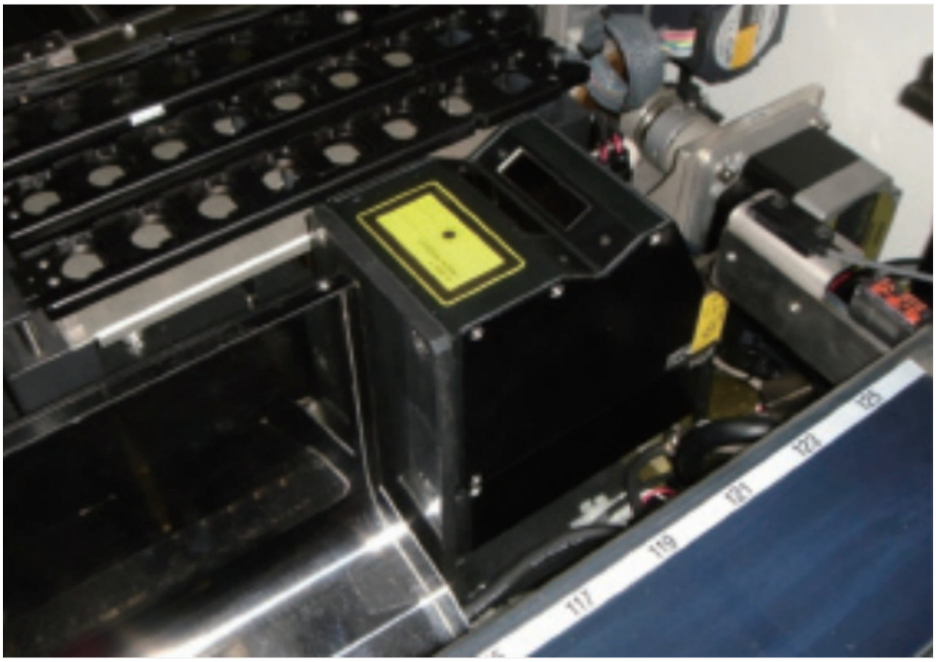
Reduces loss in tact time

To increase productivity, the unit features flying vision and flying nozzle change functions, which respectively perform parts recognition and nozzle changes, while the head is in motion after picking up or placing parts.



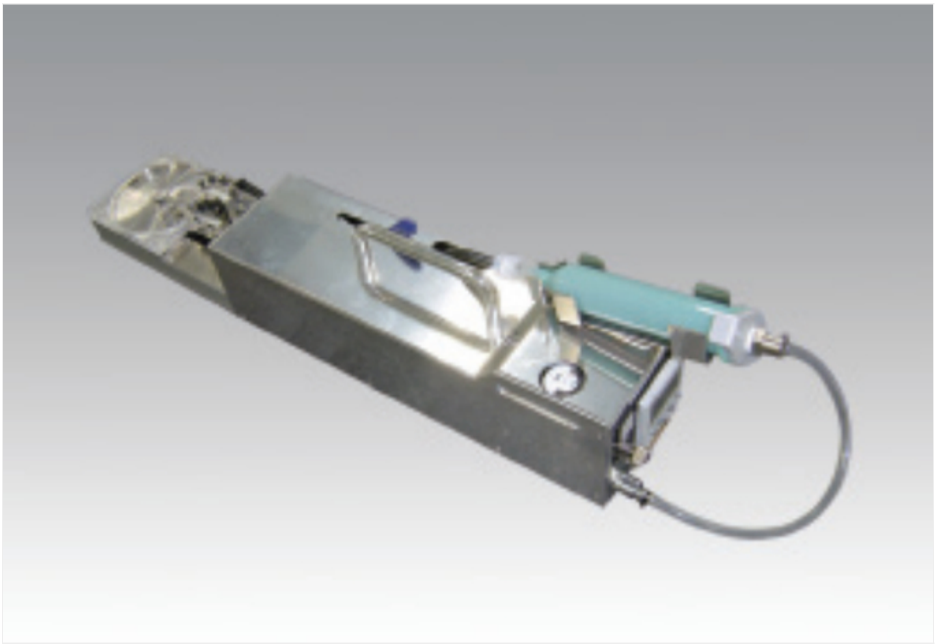
Coplanarity system

This system inspects leads and solder balls of the large parts such as QFP and BGA.



Dip Unit

This is a flux and solder paste coating unit for POP mounting. Coating material is supplied automatically.



PDX (Product Explorer)

Receives and distributes production data and performs device management at will. Improves your productivity, traceability and quality levels through remote machine control.

CPS Pro 4

This software optimizes the layout of nozzles and parts supply on all the SI series. Equipped with the same GUI as the unit's display, it is even easier to use.